

整机柜架构中的电源与散热管理 Power and Thermal Management in Rack Scale Architecture

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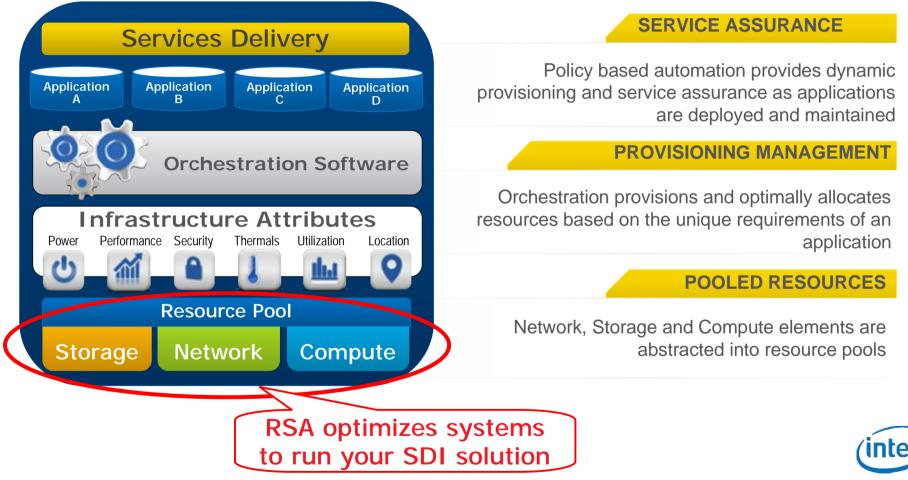
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- Rack Scale Management Architecture Overview
- Power Events Management in Rack Scale Architecture
- Advanced Thermal Management in Rack Scale Architecture
- Summary
- Q&A

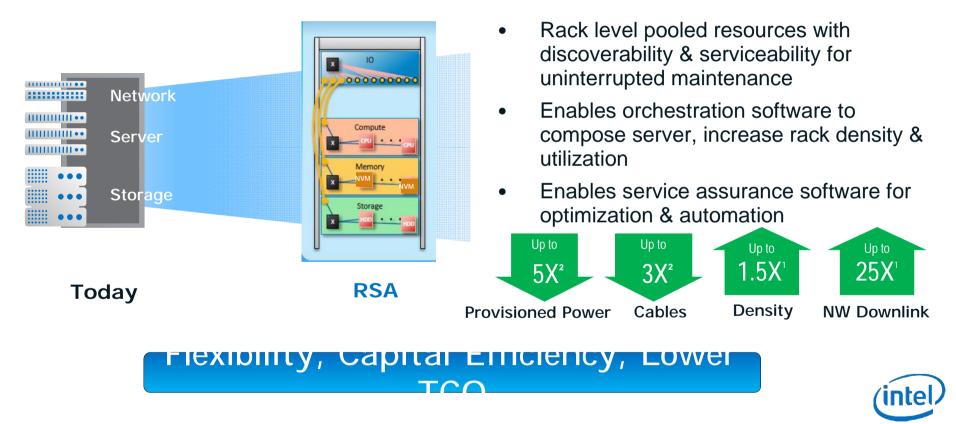


Software Defined Infrastructure

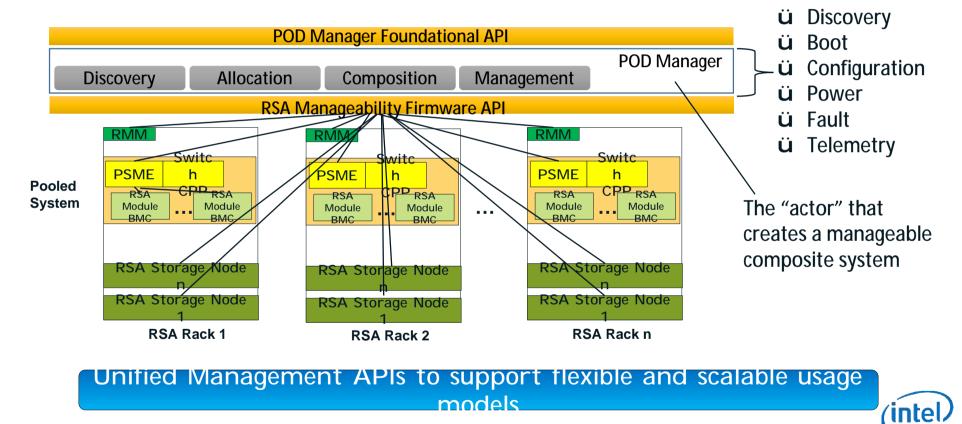


Intel® Rack Scale Architecture – Optimized for SDI

Discrete Components, Self-Integration Composable set of pooled and disaggregated resources



RSA Management Architecture System Level Strawman



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Power Events in Rack Scale Architecture

- ü Over current
- ü Power supply module overheat
- ü Power supply module failure
- ü Main power temporary loss / interrupt
- ü Main power out of range

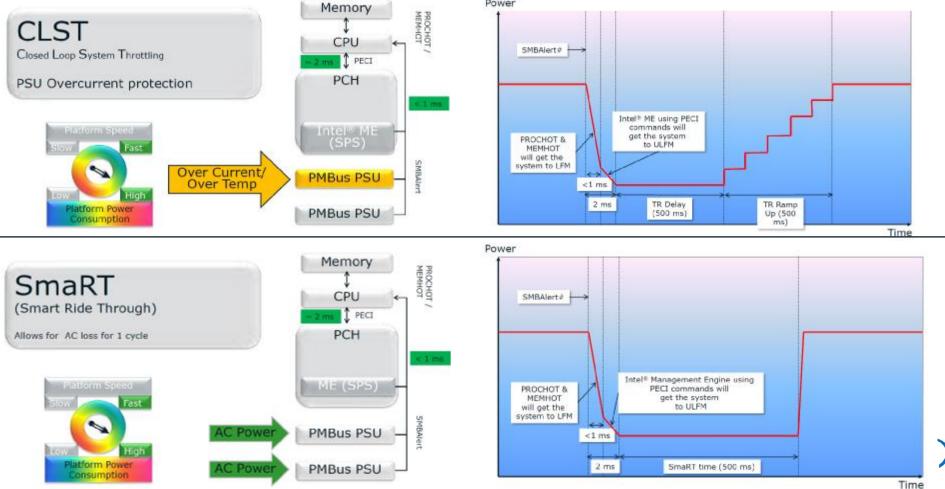


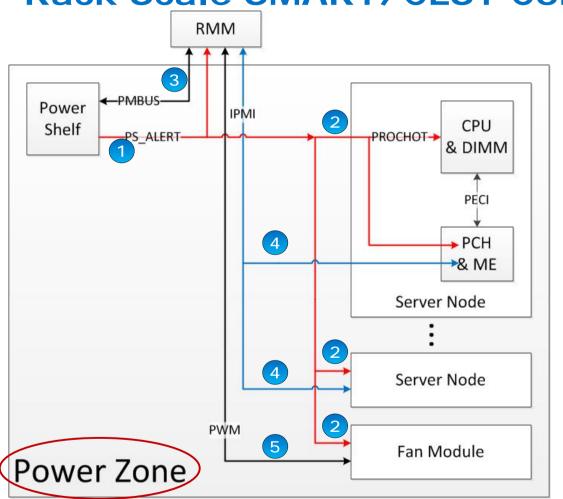
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Shared Power Supply in RSA Requires More Sophisticated Power Events Management



Power Events Management: CLST and SMART





Rack Scale SMART/CLST Concept

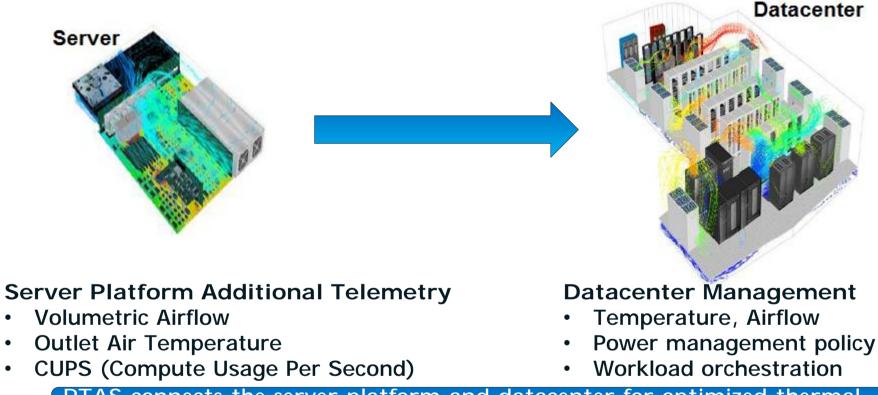
- Power Shelf asserts
 PS_ALERT upon the power event occurs;
- (2) PS_ALERT triggers CPU/DIMM throttling, and set Fans to the low power mode;
- (3) PS_ALERT also triggers RMM to poll Power Shelf for the event information;
- (4) RMM informs the Server Nodes for the next actions;

RIVINIT to Server Nodes and Power Shelf communications are based on RSA manageability API (intel

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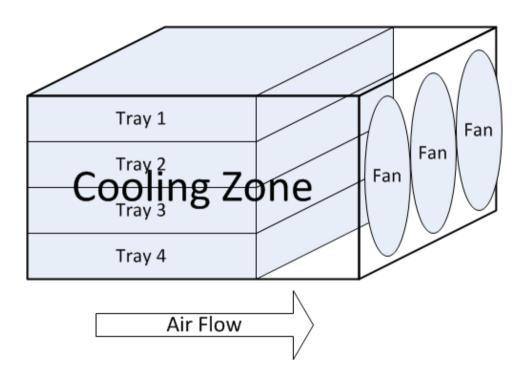
PTAS (Power Thermal Aware Solution)



PTAS connects the server platform and datacenter for optimized thermal control

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Rack Scale Level PTAS Concept



Basic Theory:

Q=f(RPM)

[1]

Where:

Q is the Volumetric Airflow of the cooling zone; RPM is the speed (rotate per minute) of the fans.

 $T_{outlet} = T_{inlet} + 1.76 * P * k_{alt}/Q$ [2] Where:

 T_{outlet} is the outlet temperature of the cooling zone. T_{inlet} is the inlet temperature of the cooling zone. P is the total power dissipation of the cooling zone; k_{alt} is the altitude correction factor.

Q is the Volumetric Airflow of the cooling zone;

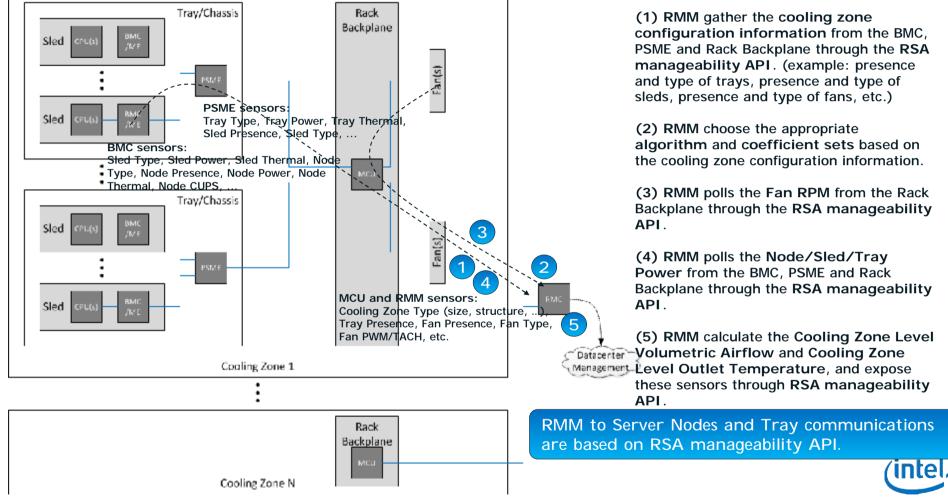
Challenges at Rack Scale:

- Function 1 is highly correlated to the cooling zone configuration, e.g. number and types of the trays.
- Equation 2 needs real time power data from all components within the cooling zone.

Need to support the dynamical configuration of the cooling zone



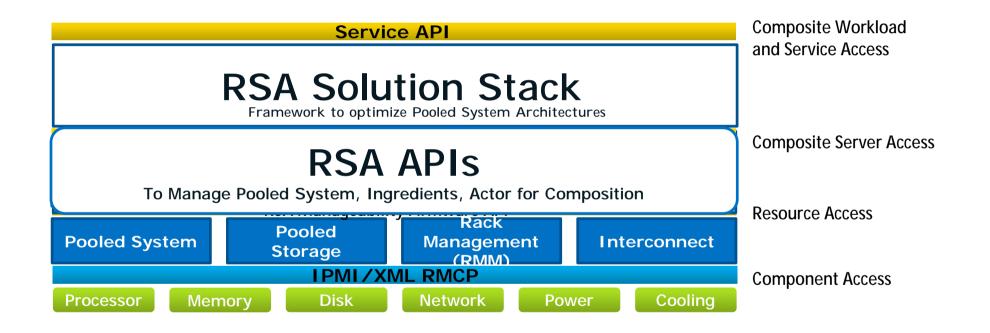
Rack Scale PTAS Implementation using RSA Manageability API



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Rack Scale Software Architecture





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Backup



RSA: Physical Manifestation

